

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	WAN-YU KAI	01/17/2024
	CHIA-WEI HU	01/17/2024
	TA-CHUAN KUO	01/17/2024
RECEIVING PARTY DATA		
Name:	DIODES INCORPORATED	
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City:	PLANO	
State/Country:	TEXAS	
Postal Code:	75024	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	18416776	
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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Correspondent Name:	AP3 LAW FIRM	
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ATTORNEY DOCKET NUMBER:	2023-061-D-US	
NAME OF SUBMITTER:	DENISE WILSON	
SIGNATURE:	/Denise Wilson/	
DATE SIGNED:	01/18/2024	
Total Attachments: 1		
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ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

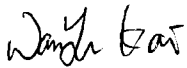
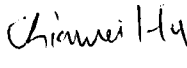

WHEREAS, Diodes Incorporated ("Assignee"), a corporation organized and existing under the law of the state of Delaware, with its principal office at 4949 Hedgcoxe Road, Suite 200, Plano, TX 75024, U.S., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application(s) and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patents resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to said Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, of the Paris Convention, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE	Power MOSFET with Gate-Source ESD Diode Structure			
SIGNATURE OF INVENTOR				
PRINTED NAME OF INVENTOR	Wan-Yu Kai	Chia-Wei Hu	Ta-Chuan Kuo	
DATE	2024.1.17	2024.1.17	2024.1.17	
RESIDENCE	TW	TW	TW	